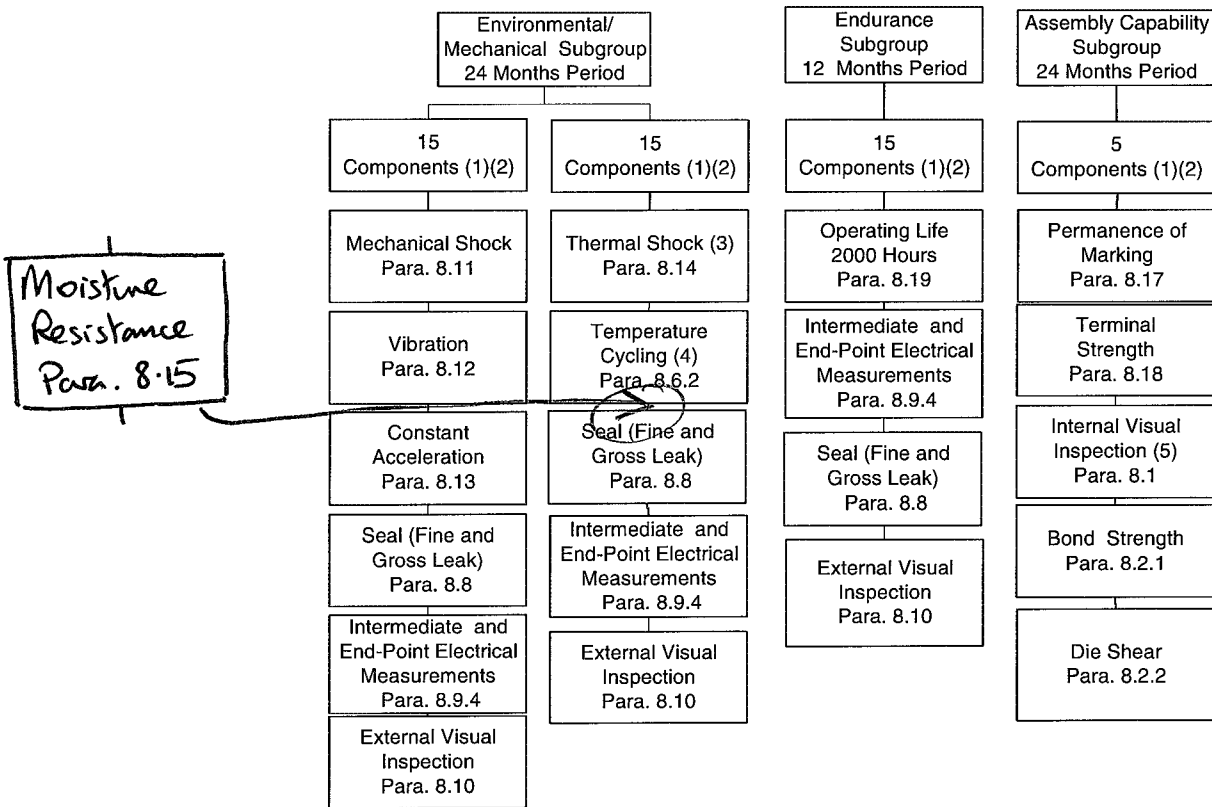




- point prior to Initial measurements of Parameter Drift Values.
2. The lot failure criteria of Para. 6.4 apply to this test.
3. Performed on a sample basis.
4. For components with hot solder dip final lead finish the hot solder dip processing shall be performed at any time prior to Room Temperature Electrical Measurements during Screening Tests. The requirements for hot solder dip are specified in ESCC Basic Specification No. 23500.
5. Measurements of Parameter Drift Values need not be repeated in Room Temperature Electrical Measurements.
6. Check for Lot Failure shall take into account all electrical parameter failures that may occur during Screening Tests in accordance with Para. 8.9.1, 8.9.2, 8.9.3 subsequent to HTRB Burn-in.
7. Radiographic Inspection may be performed at any point during Screening Tests after serialisation. It is not applicable for diodes with transparent packages.

12.4 CHART F4 - QUALIFICATION AND PERIODIC TESTS



NOTES:

1. For distribution within the subgroups see Para. 7.1.2 for qualification and qualification maintenance and Para. 7.4 for Lot Validation Testing.
2. No failures are permitted.
3. Only applicable to axial lead glass diodes.
4. Not applicable to axial lead glass diodes.
5. The components shall be deencapsulated using suitable means to facilitate Internal Visual Inspection, Bond Strength and Die Shear.